860

Silicone Heat Transfer Compound

860 is a thermal paste designed to reduce thermal resistance between irregular metal surfaces. Coupled with reasonable thermal conductivity, it has a soft consistency and a wide operating temperature range, making it an ideal thermal paste for CPU applications.

This silicone-based thermal paste is mostly used to improve heat flow between heat sinks and heat-generating components, such as CPUs, GPUs, LEDs, motors, and power components.



Features & Benefits

- High dielectric strength
- Excellent corrosion resistance
- Non-bleeding heat transfer paste
- Non-electrically conductive
- Long service life

Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
860-4G	Pouch	1.7 mL	4 g
860-60G	Jar	25 mL	60 g
860-150G	Tube	62.5 mL	150 g
860-1P	Jar	470 mL	1.13 kg
860-3.78L	Pail	3.78 L	9.07 kg

Storage and Handling

Store between 0 and 30 °C in a dry area, away from sunlight (see SDS).

Properties

Color	White	
Filler	Zinc oxide	
Base Material	Silicone oil	
Density	2.4	g/mL
Viscosity	490	Pa·s
Resistivity	1.5×10^{15}	Ω·cm
Thermal Conductivity @ 25 ˚C	0.7	W/(m·K)
Evaporation Loss, 22 h @ 165 ˚C	0.1	%
Oil Separation, 30 h @ 165 ˚C	0.7	%
Worked Penetration, ½ scale	303	
Water Washout @ 38 ˚C, Bearing Dried @ 77 ˚C	0.1	%
Dielectric Strength	400	V/mil
Dielectric Constant	3.8	
Dissipation Factor	0.003	
Service Temperature Range	-40–200	˚C

Contact Information

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